PowerMOS transistor
Fast Recovery Diode FET

BUK637-400A
BUK637-400B

T-39-15

GENERAL DESCRIPTION

N-channel enhancement mode field-effect power transistor in a plastic envelope.
FREDFET with fast recovery reverse diode, particularly suitable for motor control applications, eg. in full bridge configurations for which faster recovery characteristics simplify design for inductive loads.

QUICK REFERENCE DATA

SYMBOL	PARAMETER	MAX.	MAX.	UNIT
		BUK637 -400A	-400B	
V_{DS}	Drain-source voltage	400	400	V
I_D	Drain current (DC)	14	12	A
P_{tot}	Total power dissipation	180	180	W
$R_{DS(ON)}$	Drain-source on-state resistance	0.5	0.6	Ω
t_{rr}	Diode reverse recovery time	250	250	ns

MECHANICAL DATA

Dimensions in mm

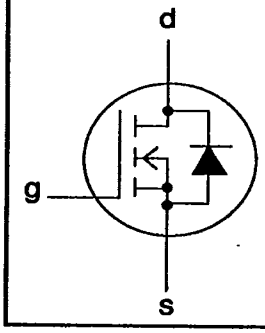
Net Mass: 5 g

Pinning:

1 = Gate

2 = Drain

3 = Source



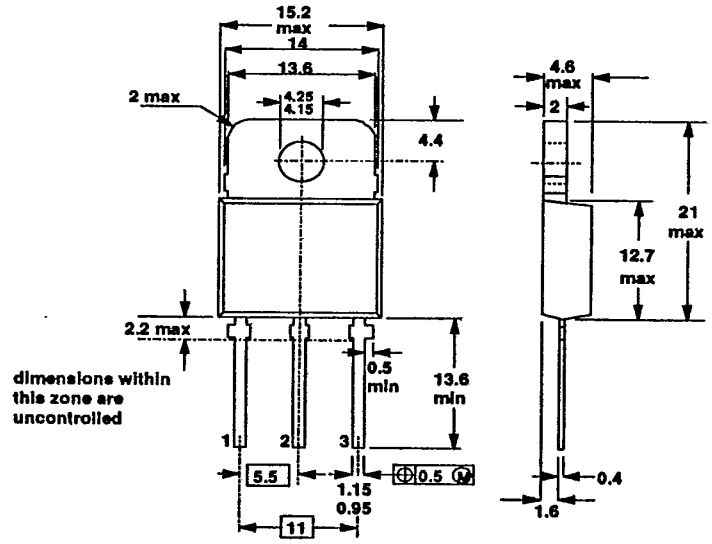


Fig.1 SOT-93; drain connected to mounting base.

Notes
1. Observe the general handling precautions for electrostatic-discharge sensitive devices (ESDs) to prevent damage to MOS gate oxide.
2. Accessories supplied on request: refer to Mounting instructions for SOT93 envelope.

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RATINGS

Limiting values in accordance with the Absolute Maximum System (IEC 134)

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.		UNIT
V_{DS}	Drain-source voltage	-	-	400		V
V_{DGR}	Drain-gate voltage	R_{GS} = 20 kΩ	-	400		V
$\pm V_{GS}$	Gate-source voltage	-	-	30		V
				-400A	-400B	
I_D	Drain current (DC)	T_{mb} = 25 °C	-	14	12	A
I_D	Drain current (DC)	T_{mb} = 100 °C	-	8.8	7.6	A
I_{DM}	Drain current (pulse peak value)	T_{mb} = 25 °C	-	56	48	A
P_{tot}	Total power dissipation	T_{mb} = 25 °C	-	180		W
T_{stg}	Storage temperature	-	-55	150		°C
T_j	Junction Temperature	-	-	150		°C

THERMAL RESISTANCES

From junction to mounting base	$R_{th\ j\text{-}mb}$ = 0.69 K/W
From junction to ambient	$R_{th\ j\text{-}a}$ = 45 K/W

STATIC CHARACTERISTICS

T_{mb} = 25 °C unless otherwise specified

SYMBOL	PARAMETER	CONDITIONS		MIN.	TYP.	MAX.	UNIT
$V_{(BR)DSS}$	Drain-source breakdown voltage	V_{GS} = 0 V; I_D = 0.25 mA		400	-	-	V
$V_{GS(TO)}$	Gate threshold voltage	V_{DS} = V_{GS}; I_D = 1 mA		2.1	3.0	4.0	V
I_{DSS}	Zero gate voltage drain current	V_{DS} = 400 V; V_{GS} = 0 V; T_j = 25 °C		-	2	20	μA
I_{DSS}	Zero gate voltage drain current	V_{DS} = 400 V; V_{GS} = 0 V; T_j = 125 °C		-	0.1	1.0	mA
I_{GSS}	Gate source leakage current	V_{GS} = ±30 V; V_{DS} = 0 V		-	10	100	nA
$R_{DS(ON)}$	Drain-source on-state resistance	V_{GS} = 10 V; I_D = 6.5 A	BUK637-400A	-	0.4	0.5	Ω
			BUK637-400B	-	0.5	0.6	Ω

DYNAMIC CHARACTERISTICS

T_{mb} = 25 °C unless otherwise specified

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
g_{fs}	Forward transconductance	V_{DS} = 25 V; I_D = 6.5 A	5.0	8.0	-	S
C_{iss}	Input capacitance	V_{GS} = 0 V; V_{DS} = 25 V; f = 1 MHz	-	1500	1800	pF
C_{oss}	Output capacitance		-	170	270	pF
C_{rss}	Feedback capacitance		-	70	120	pF
$t_{d\ on}$	Turn-on delay time	V_{DD} = 30 V; I_D = 2.8 A;	-	20	40	ns
t_r	Turn-on rise time	V_{GS} = 10 V; R_{GS} = 50 Ω;	-	60	90	ns
$t_{d\ off}$	Turn-off delay time	R_{gen} = 50 Ω	-	200	250	ns
t_f	Turn-off fall time		-	75	90	ns
L_d	Internal drain inductance	Measured from contact screw on tab to centre of die	-	5	-	nH
L_d	Internal drain inductance	Measured from drain lead 6 mm from package to centre of die	-	5	-	nH
L_s	Internal source inductance	Measured from source lead 6 mm from package to source bond pad	-	12.5	-	nH

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REVERSE DIODE RATINGS AND CHARACTERISTICS

T_{mb} = 25 °C unless otherwise specified

SYMBOL	PARAMETER	CONDITIONS		MIN.	TYP.	MAX.	UNIT
I_{DR}	Continuous reverse drain current	-		-	-	14	A
I_{DRM}	Pulsed reverse drain current	-		-	-	56	A
V_{SD}	Diode forward voltage	I_F = 14 A ;	V_{GS} = 0 V	-	1.1	1.5	V
t_{rr}	Reverse recovery time	I_F = 14 A;	T_j - 25 °C	-	180	250	ns
		$-dI_F/dt$ =	T_j - 125 °C	-	220	300	ns
Q_{rr}	Reverse recovery charge	100 A/µs;	T_j - 25 °C	-	0.65	1.2	µC
		V_{GS} = 0 V;	T_j - 125 °C	-	2.6	5.0	µC
I_{rrm}	Reverse recovery current	V_R = 100 V	T_j - 125 °C	-	15	-	A

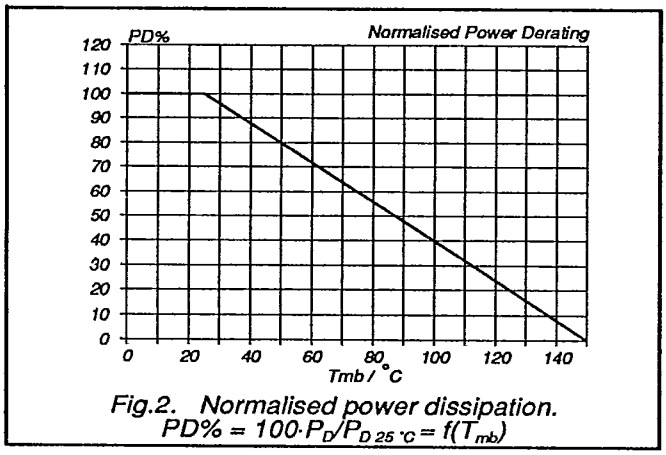

Fig.2. Normalised power dissipation.
PD% = 100·P_D/$P_{D\,25\,°C}$ = f(T_{mb})

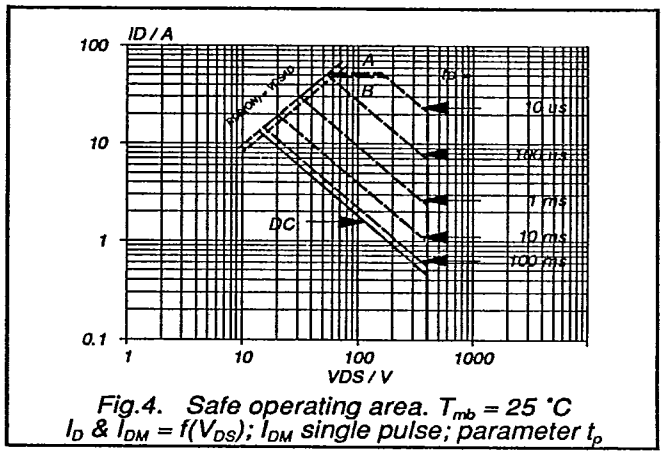

Fig.4. Safe operating area. T_{mb} = 25 °C
I_D & I_{DM} = f(V_{DS}); I_{DM} single pulse; parameter t_p

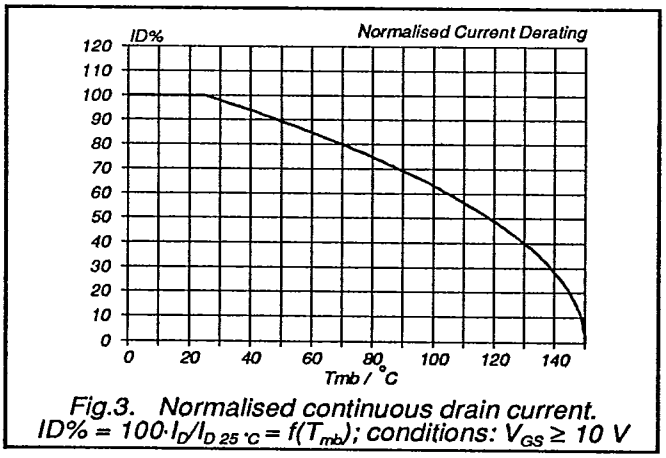

Fig.3. Normalised continuous drain current.
ID% = 100·I_D/$I_{D\,25\,°C}$ = f(T_{mb}); conditions: V_{GS} ≥ 10 V

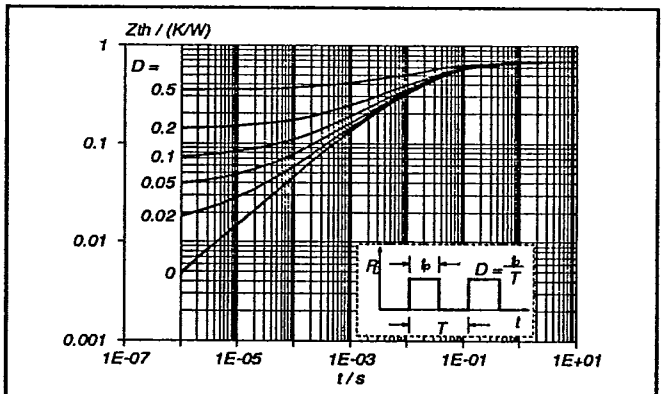

Fig.5. Transient thermal impedance.
$Z_{th\,j\text{-}mb}$ = f(t); parameter D = t_p/T

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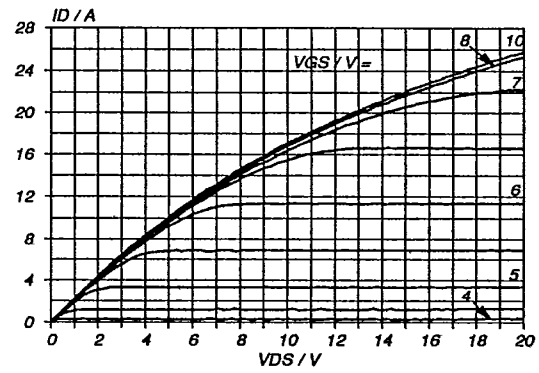

Fig.6. Typical output characteristics, $T_j = 25$ °C. $I_D = f(V_{DS})$; parameter V_{GS}

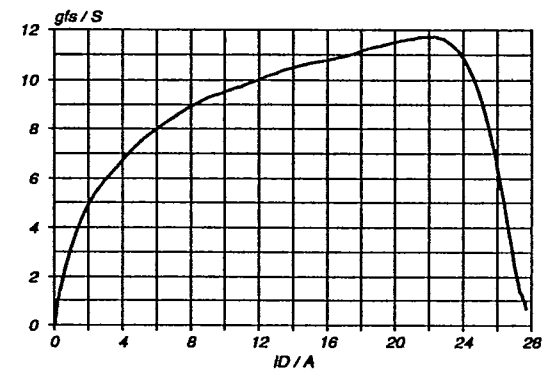

Fig.9. Typical transconductance, $T_j = 25$ °C. $g_{fs} = f(I_D)$; conditions: $V_{DS} = 25$ V

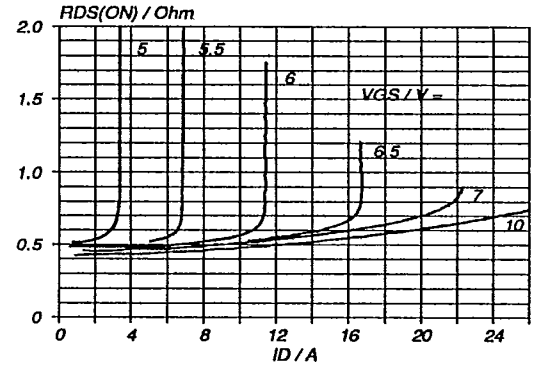

Fig.7. Typical on-state resistance, $T_j = 25$ °C. $R_{DS(ON)} = f(I_D)$; parameter V_{GS}

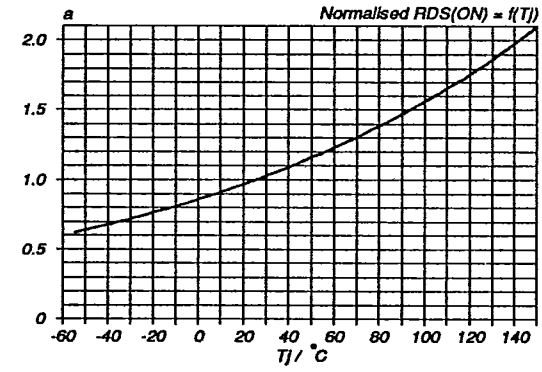

Fig.10. Normalised drain-source on-state resistance. $a = R_{DS(ON)}/R_{DS(ON)25\,°C} = f(T_j)$; $I_D = 6.5$ A; $V_{GS} = 10$ V

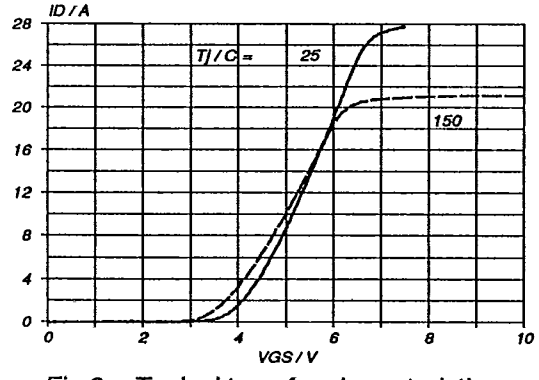

Fig.8. Typical transfer characteristics. $I_D = f(V_{GS})$; conditions: $V_{DS} = 25$ V; parameter T_j

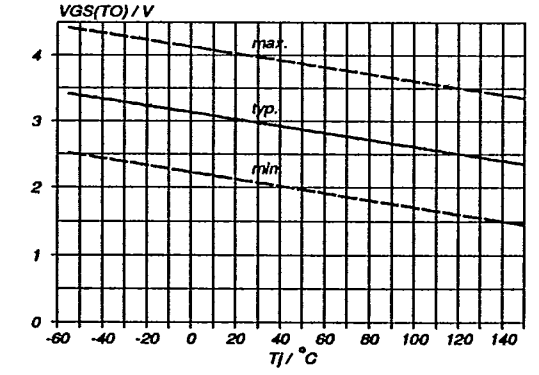

Fig.11. Gate threshold voltage. $V_{GS(TO)} = f(T_j)$; conditions: $I_D = 1$ mA; $V_{DS} = V_{GS}$

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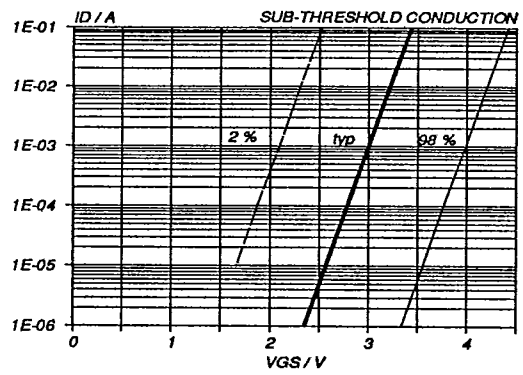

Fig.12. Sub-threshold drain current.
$I_D = f(V_{GS})$; conditions: $T_j = 25$ °C; $V_{DS} = V_{GS}$

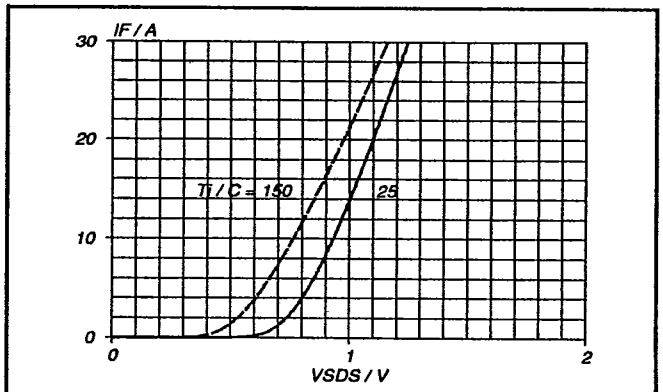

Fig.15. Typical reverse diode current.
$I_F = f(V_{SDS})$; conditions: $V_{GS} = 0$ V; parameter T_j

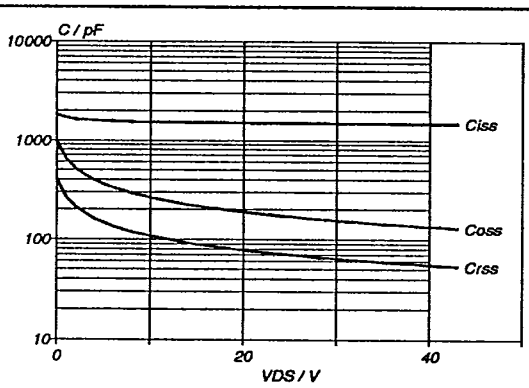

Fig.13. Typical capacitances, C_{iss}, C_{oss}, C_{rss}.
$C = f(V_{DS})$; conditions: $V_{GS} = 0$ V; $f = 1$ MHz

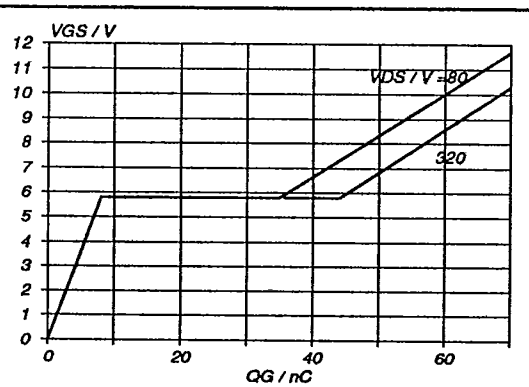

Fig.14. Typical turn-on gate-charge characteristics.
$V_{GS} = f(Q_G)$; conditions: $I_D = 14$ A; parameter V_{DS}